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•	I ² C Bus Controllable 2-W/Ch Output Power Into 4-Ω Load	PWP PACKAGE (TOP VIEW)			
•	Low Supply Current and Shutdown Current	GND □□	1 0 2	24 LOUT-	
•	Depop Circuitry	LOUT+ 🗀	_	23 SCL	
•	Digital Volume Control From 20 dB to	PC-BEEP	-	22 SHUTDOWN	
	-60 dB	ADDRESS0		BYPASS	
•	Internal Gain Control, Which Eliminates	LIN —— LLINEIN ——	-	20	
	External Gain-Setting Resistors		-	18 RLINEIN	
•	Fully Differential Input	PV _{DD} □□	8	7 RHPIN	
•	Stereo Input MUX	RIN 🗀	-	16 D I2CV _{DD}	
_	•	ADDRE <u>SS1</u>	10 1	5 DA SDA	
	PC-Beep Input	SE/BTL 🗀	11 1	4	
•	Compatible With PC 99 Desktop Line-Out Into 10-kΩ Load	ROUT+ 🗀	12	3 GND	
•	Compatible With PC 99 Portable Into 8- Ω				

description

Load

Surface-Mount Power Packaging 24-Pin TSSOP PowerPAD™

The TPA0172 is a stereo audio power amplifier in a 24-pin TSSOP thermally enhanced package capable of delivering 2 W of continuous RMS power per channel into 4- Ω loads. This device utilizes the I²C bus to control its functionality, which minimizes the number of external components needed, simplifies the design, and frees up board space for other features. When driving 1 W into 8- Ω speakers, the TPA0172 has less than 0.2% THD+N from 20 Hz to 20 kHz.

Included within this device is integrated depop circuitry that virtually eliminates transients that cause noise in the speakers at power up, power down, and while transitioning in and out of shutdown mode.

The overall gain of the amplifier is controlled digitally by the volume control registers which are programmed via the I²C interface. At power up, the amplifier defaults to -60 dB in BTL mode, or -66 dB in SE mode. There are four registers that contain the gains: left BTL, right BTL, left SE, and right SE. Each register contains six bits, which allows 64 gain steps from -60 dB to 20 dB in 1.25-dB steps, and two bits that mute the amplifier.

The TPA0172 only consumes 6.5 mA of supply current during normal operation. A shutdown mode is included that reduces supply current to less than 15 µA.

The PowerPAD package (PWP) delivers a level of thermal performance that was previously achievable on TO-200-type packages. Thermal impedances of approximately 35°C/W are truly realized in multilayer PCB applications. This allows the TPA0172 to operate at full power into $8-\Omega$ loads at ambient temperatures of 85° C.

AVAILABLE OPTIONS

	PACKAGED DEVICE	
TA	TSSOP†	
	(PWP)	
-40°C to 85°C	TPA0172PWP	

[†] The PWP package is available taped and reeled. To order a taped and reeled part, add the suffix R to the part number (e.g., TPA0172PWPR).

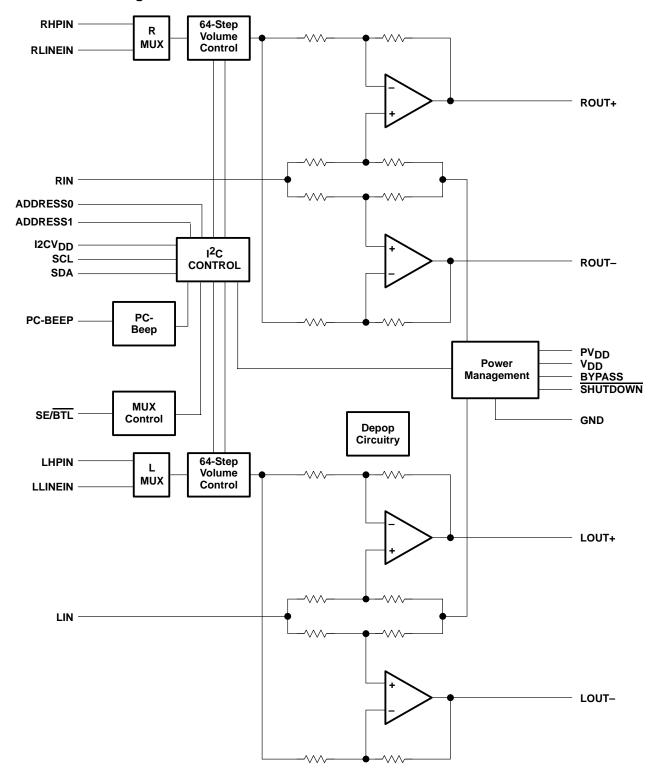


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments.



functional block diagram





Terminal Functions

TERMINAL						
NAME	NO.		DESCRIPTION			
ADDRESS0	4	ı	Bit 0 of user-setable portion of device's I ² C address.			
ADDRESS1	10	I	Bit 1 of user-setable portion of device's I ² C address.			
BYPASS	21		Tap to voltage divider for internal midsupply bias generator.			
GND	1, 13		Ground connection for circuitry. Connect to thermal pad			
LHPIN	7	I	Left-channel headphone input, selected when SE/BTL is held high, or programmed via I ² C.			
LIN	5	I	Common left input for fully differential input. AC ground for single-ended inputs.			
LLINEIN	6	I	Left-channel line input, selected when SE/BTL is held low, or programmed via I ² C.			
LOUT+	2	0	Left-channel positive output in BTL mode, and positive output in SE mode.			
LOUT-	24	0	Left-channel negative output in BTL mode, and high impedance in SE mode.			
PC-BEEP	3	ı	The input for PC-BEEP mode which is enabled when a > 1-V (peak-to-peak) square wave is input to this terminal, when PCB ENABLE is held high, or programmed via I ² C. If not used, ground this terminal.			
I2CV _{DD}	16	I	The voltage on this terminal sets the trip points for the I^2C interface. If the system I^2C bus is running at 3 then tie this terminal to 3.3 V. If the system I^2C bus is running at 5 V, then tie this terminal to 5 V.			
PV_{DD}	8, 19	ı	Power supply			
RHPIN	17	ı	Right-channel headphone input, selected when SE/BTL is held high, or programmed via I ² C.			
RIN	9	- 1	Common right input for fully differential input. AC ground for single-ended inputs.			
RLINEIN	18	ı	Right-channel line input, selected when SE/BTL is held low, or programmed via I ² C.			
ROUT+	12	0	Right-channel positive output in BTL mode, and positive output in SE mode.			
ROUT-	14	0	Right-channel negative output in BTL mode, and high impedance in SE mode.			
SCL	23	ı	I ² C clock line			
SDA	15		Serial data line of the I ² C bus. Pullup resistor must comply with the I ² C standard: minimum value = $3 \text{ k}\Omega$, maximum value = $19 \text{ k}\Omega$. Pull up to I2CVDD			
SE/BTL	11	Ţ	Input MUX control input. When this terminal is held high, the LHPIN or RHPIN, and the SE output are selected. When this terminal is held low, the LLINEIN or RLINEIN, and the BTL output are selected. This functionality can also be programmed via I ² C.			
SHUTDOWN	22	I	When held low, this terminal places the device in the shutdown mode, except for the PC-BEEP input and I ² C bus.			
V_{DD}	20	ı	Power supply			



TPA0172 2-W STEREO AUDIO POWER AMPLIFIER WITH I²C BUS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{DD}	6 V
Bus voltage, I2CV _{DD}	6 V
Input voltage, V _I	
Continuous total power dissipation	. Internally Limited (see Dissipation Rating Table)
Operating free-air temperature range, T _A	–40°C to 85°C
Operating junction temperature range, T _J	–40°C to 150°C
Storage temperature range, T _{stq}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 second	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ} \mbox{C}$	DERATING FACTOR	T _A = 70°C	T _A = 85°C
PWP	2.7 W [‡]	21.8 mW/°C	1.7 W	1.4 W

[‡] See the Texas Instruments document, PowerPAD™ Thermally Enhanced Package Application Report (literature number SLMA002), for more information on the PowerPAD™ package. The thermal data was measured on a PCB layout based on the information in the section entitled Texas Instruments Recommended Board for PowerPAD™ on page 33 of the before mentioned document.

recommended operating conditions

		MIN	MAX	UNIT	
Supply voltage, V _{DD}	4.5	5.5	V		
Bus voltage, I2CV _{DD} (see Note1)		3	5.5	V	
	SE/BTL	4		٧	
High level input valtage V.	SHUTDOWN	2			
High-level input voltage, V _{IH}	ADDRESS0, ADDRESS1	3.5			
	SDA, SCL	0.7 I2CV _{DD}			
	SE/BTL		3		
Low lovel input veltage. Viv	SHUTDOWN		0.8	V	
Low-level input voltage, V _{IL}	ADDRESS0, ADDRESS1		0.8		
	SDA, SCL	0.3 12	2CV _{DD}		
Operating free-air temperature, T _A		-40	85	°C	

NOTE 1: I2CV_{DD} must be less than or equal to V_{DD}.



electrical characteristics at specified free-air temperature, V_{DD} = 5 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
IVosl	Output offset voltage (measured differentially)	$V_{I} = 0 V$, $A_{V} = 20 dB$			20	mV
PSRR	Power supply rejection ratio	V _{DD} = 4.5 V to 5.5 V		75		dB
IIIII	High-level input current	$V_{DD} = 5.5 \text{ V}, \qquad V_{I} = V_{DD}$			1	μΑ
I _{IL}	Low-level input current	$V_{DD} = 5.5 \text{ V}, \qquad V_{I} = 0 \text{ V}$			1	μΑ
Zi	Input impedance		7.5			kΩ
I _{DD}	Supply current	BTL mode		8	12	mA
I _{DD(SD)}	Cumply surrent shutdown made	PC-BEEP = 0 V		15	35	μΑ
	Supply current, shutdown mode	PC-BEEP = V _{DD} /2		50	90	μΑ

operating characteristics, V_{DD} = 5 V, T_A = 25°C, R_L = 4 Ω , Gain = 20 dB, BTL mode (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
PO	Output power	THD = 0.08%,	f = 1 kHz		2		W
THD + N	Total harmonic distortion plus noise	P _O = 1 W,	f = 20 Hz to 20 kHz	C	0.3%		
ВОМ	Maximum output power bandwidth	THD = 1%			>20		kHz
	Overally visuals unitation until	f 4111- 0 0.47F	BTL mode		-58		dB
Supply ripple rejection ratio		$f = 1 \text{ kHz}, C_B = 0.47 \mu\text{F}$	SE mode		-52		ub
, -	Noise output voltage	$\begin{split} C_B &= 0.47 \ \mu\text{F}, \\ f &= 20 \ \text{Hz} \ \text{to} \ 20 \ \text{kHz}, \\ \text{Gain} &= 6 \ \text{dB} \ \text{BTL}, \ 0 \ \text{dB} \ \text{SE} \end{split}$	BTL mode	29		/	
V _n			SE mode		23		μVRMS

TYPICAL CHARACTERISTICS

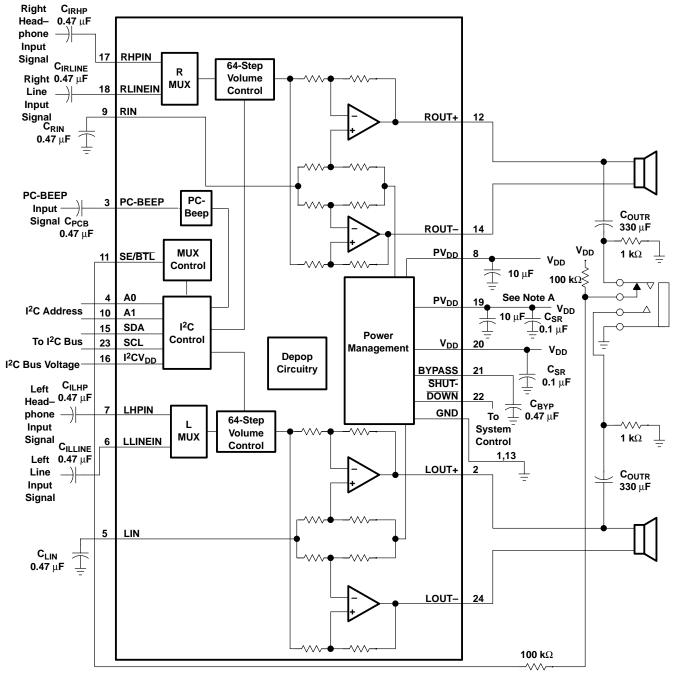
Table of Graphs

			FIGURE
THD+N	Total harmonic distortion plus noise	vs Output power	1, 2, 4, 6
I HD+N		vs Frequency	3, 5,
٧n	Output noise voltage	vs Frequency	7
	Supply ripple rejection ratio	vs Frequency	8, 9
	Crosstalk	vs Frequency	10, 11
	Shutdown attenuation	vs Frequency	12
	Closed loop response		13, 14
PO	Output power	vs Load resistance	15, 16
Do	Power dissipation	vs Output power	17, 18
PD		vs Ambient temperature	19

APPLICATION INFORMATION

selection of components

Figure 20 and Figure 21 are schematic diagrams of typical notebook computer application circuits.



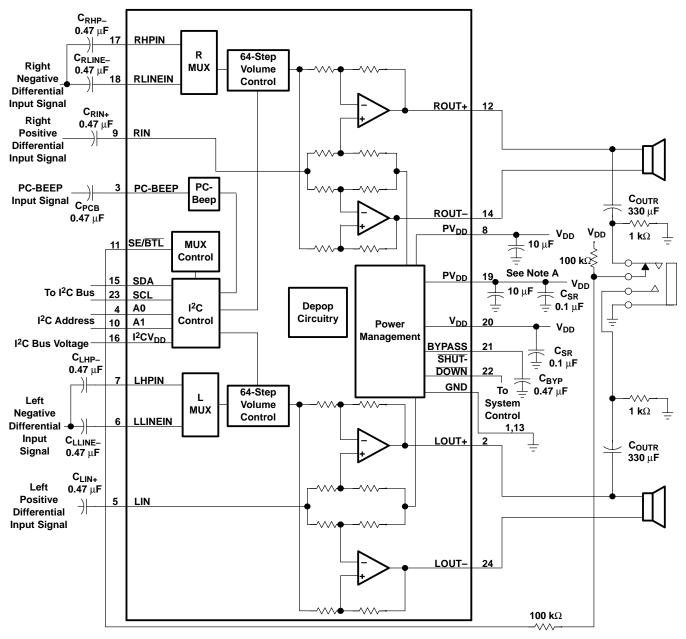
NOTE A: A 0.1- μ F ceramic capacitor should be placed as close as possible to the IC. For filtering lower-frequency noise signals, a larger electrolytic capacitor of 10 μ F or greater should be placed near the audio power amplifier.

Figure 20. Typical TPA0172 Application Circuit Using Single-Ended Inputs and Input MUX



APPLICATION INFORMATION

selection of components (continued)



NOTE A: A 0.1-μF ceramic capacitor should be placed as close as possible to the IC. For filtering lower-frequency noise signals, a larger electrolytic capacitor of 10 μF or greater should be placed near the audio power amplifier.

Figure 21. Typical TPA0172 Application Circuit Using Differential Inputs

